

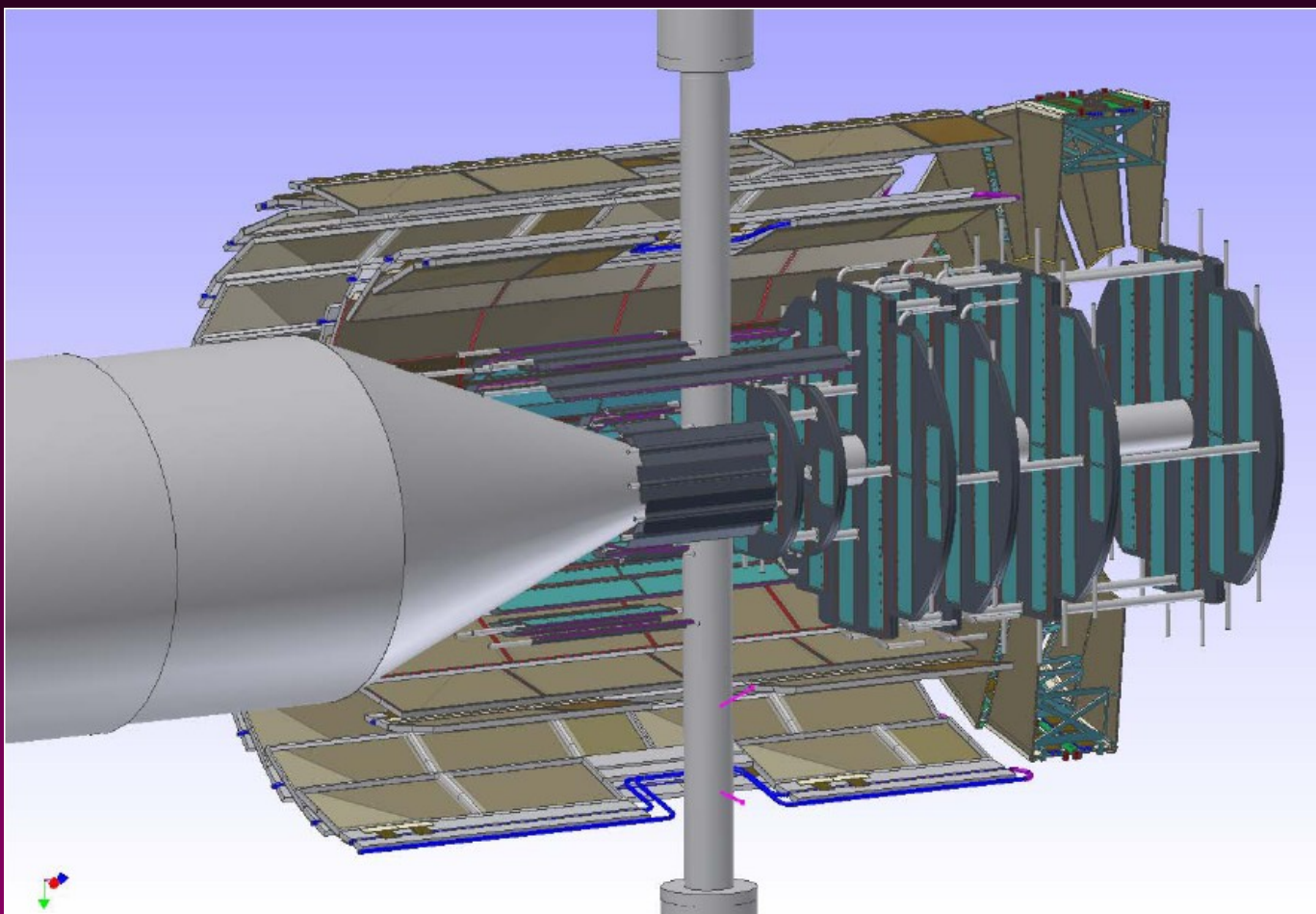


PANDA FEE-DAQ Workshop



Status report of the Silicon Pixel Detector Readout Electronics

G. Mazza
on behalf of the Torino MVD pixel group



* Barrel :

Layer 1 : radius 28 mm, SPDs

Layer 2 : radius 53 mm, SPDs

Layer 3 : radius 92 mm, SSDs

Layer 4 : radius 120 mm, SSDs

* Forward :

Disks 1-2 : radius 37.5 mm,
SPDs

Disks 3-4 : radius 75 mm, SPDs

Disks 5-6 : radius 130 mm,
SPDs + SSDs



Pixel Detector



Sezione di Torino

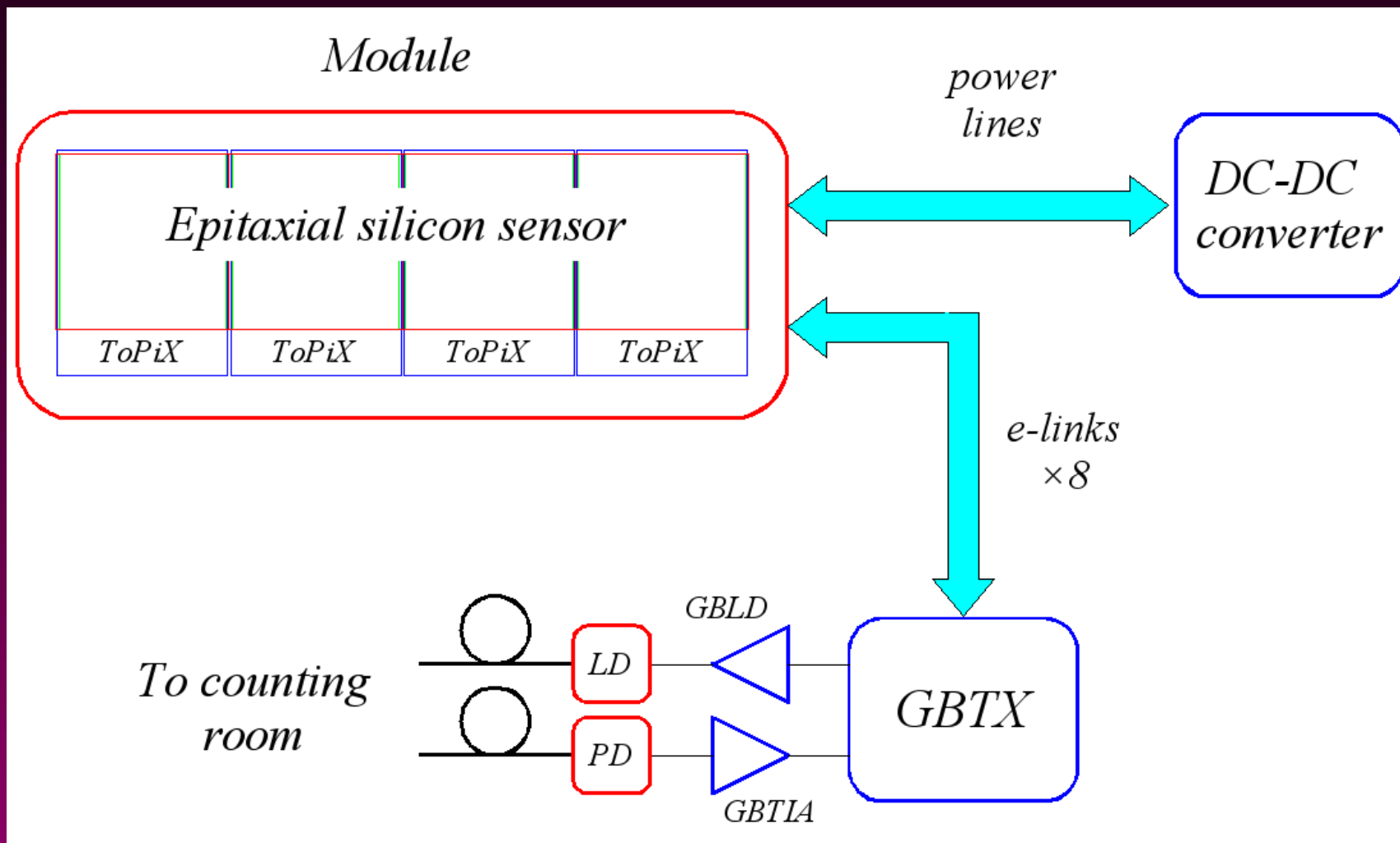
<i>Pixel size</i>	$100 \times 100 \mu\text{m}^2$
<i>Chip active area</i>	$11.4 \times 11.6 \text{ mm}^2$ (116 rows, 110 columns)
<i>dE/dx measurement</i>	ToT, 12 bits dynamic range
<i>Max input charge</i>	50 fC
<i>Noise floor</i>	<32 aC (200 e^-)
<i>Input clock frequency</i>	155.52 MHz
<i>Time resolution</i>	6.43 ns (1.86 ns r.m.s.) 12.86 ns (3.71 ns r.m.s.)
<i>Power consumption</i>	< 800 mW/cm ²
<i>Max event rate</i>	$6.1 \cdot 10^6$
<i>Total ionizing dose</i>	< 100 kGy



Module readout



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ToPiX v3



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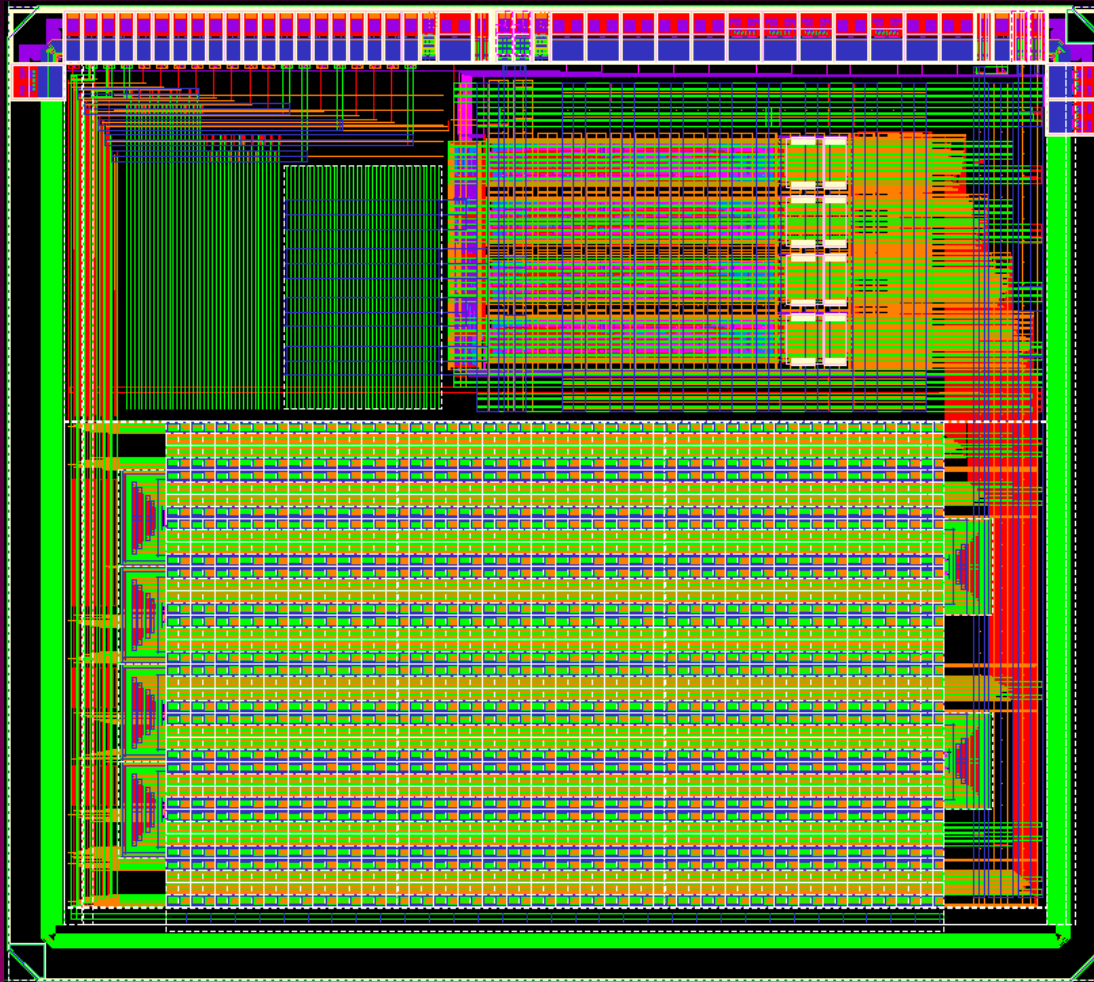
- Layout submitted on February 7th – received May 16th 2011
- 4.5x4 mm² die area
- CMOS 0.13 μm DM technology
- Triple redundancy-based SEU protection
- End of column logic
- 160 Mb/s SLVS serial output
- Pads for bump bonding



ToPiX v3 layout



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- * 4.5 mm × 4 mm
- * CMOS 130 nm
- * Clock frequency 160 MHz
- * bump bonding pads
- * 2×2×128 columns
- * 2×2×32 columns
- * 32 cells EoC FIFO
- * SEU protected EoC
- * Serial data output
- * SLVS I/O



ToPiX test results



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- * At 160MHz can only read and program first ~32 pixels of each column
- * At 50MHz (with pre-emphasis disabled) full operation
- * S-curve working well (programmable internal test pulse)
- * Baseline measurements ok
- * On-pixel DACs characterised and correction applied
- * Transfer function measurements in good agreement with simulations
- * Acquisition system is working (4 boards)
- * Tested in beam tests at CERN SPS and Julich COSY facilities
- * TID (@X ray-CERN) and SEU (@SIRAD-LNL) tests done



Open issues



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- * Clock frequency
- * Power consumption
- * Radiation tolerance
 - * TID effects
 - * SEU effects



Clock frequency problem



- * At 160 MHz only the columns with 32 double cells work correctly
- * Response improves when the frequency is decreased
- * Improvements :
 - * *Prototype full column has 30% longer bus and 10% more cells than the final chip*
 - * *Triple redundancy latches have been connected without buffers*
 - *but buffers take power !!!*
 - * *Change in the leading edge readout timing*
- * Bus estimated capacitance : 60.71 fF/dcell (v3), 49.91 fF/dcell (v4 sim. w/o buffers), 26.12 fF/dcell (v4 sim. with buffers)
- * Total bus capacitance per line : 8.30 pF (v3), 6.92 pF (v4 sim. w/o buffers), 3.88 pF (v4 sim. with buffers) – *for 128 cells and folded layout*



Timing issue

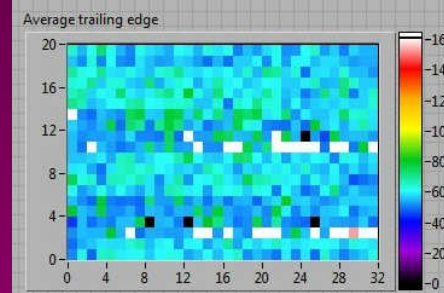
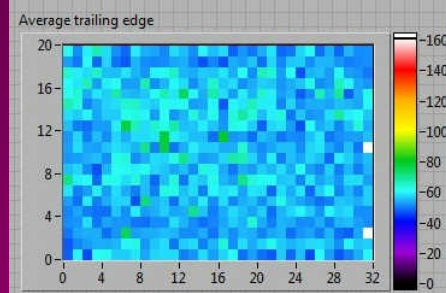
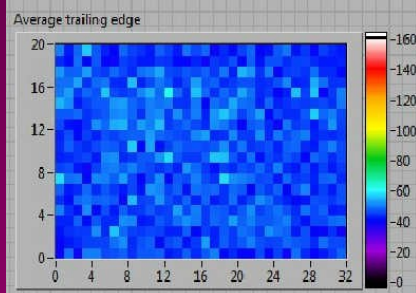
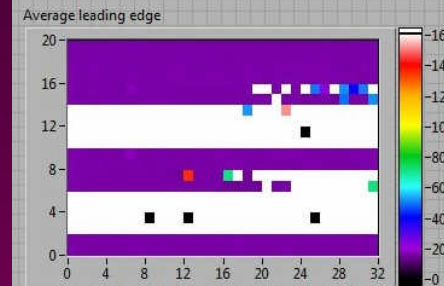
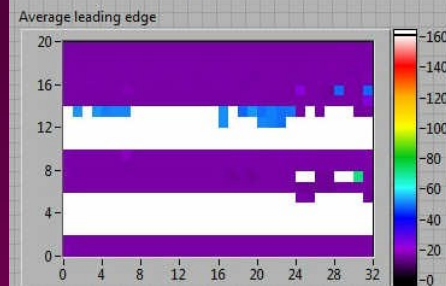
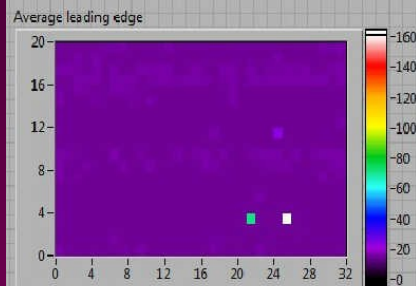
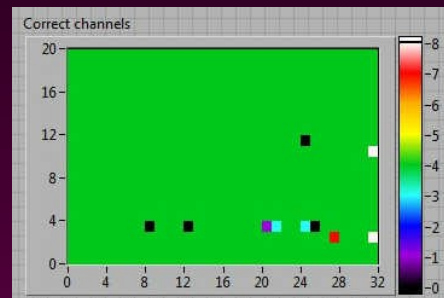
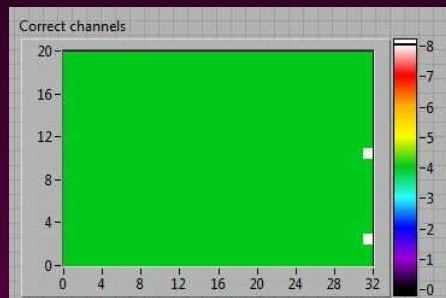
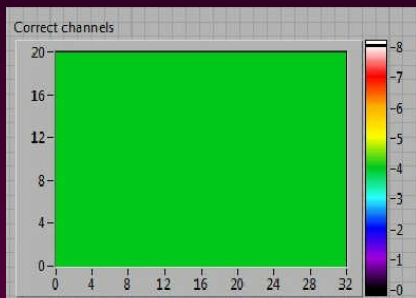


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50 MHz

65 MHz

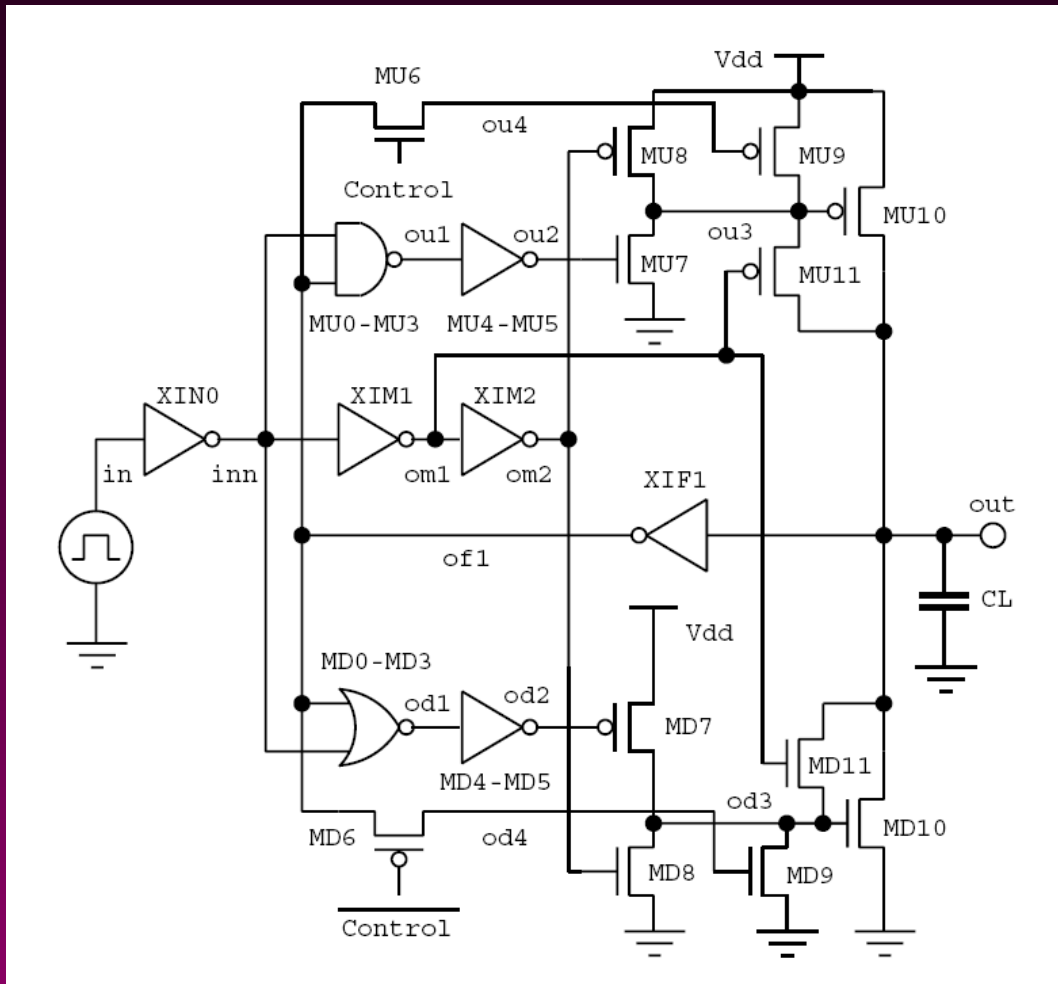
70 MHz



- * Trailing edge still good @ 65 MHz
- * Read leading edge cmd asserted at the same time as read cmd.
- * Read trailing edge cmd asserted when read cmd is already high
- * *Clock cycle to be inserted between read cmd and read leading edge cmd.*

Provides both reduced voltage swing and pre-emphasis or full voltage swing

J.C.Garcia, J.A.Montiel, S.Nooshabadi
 Adaptive Low/High Voltage Swing
 CMOS Driver for On-Chip Interconnects
 ISCAS 2007

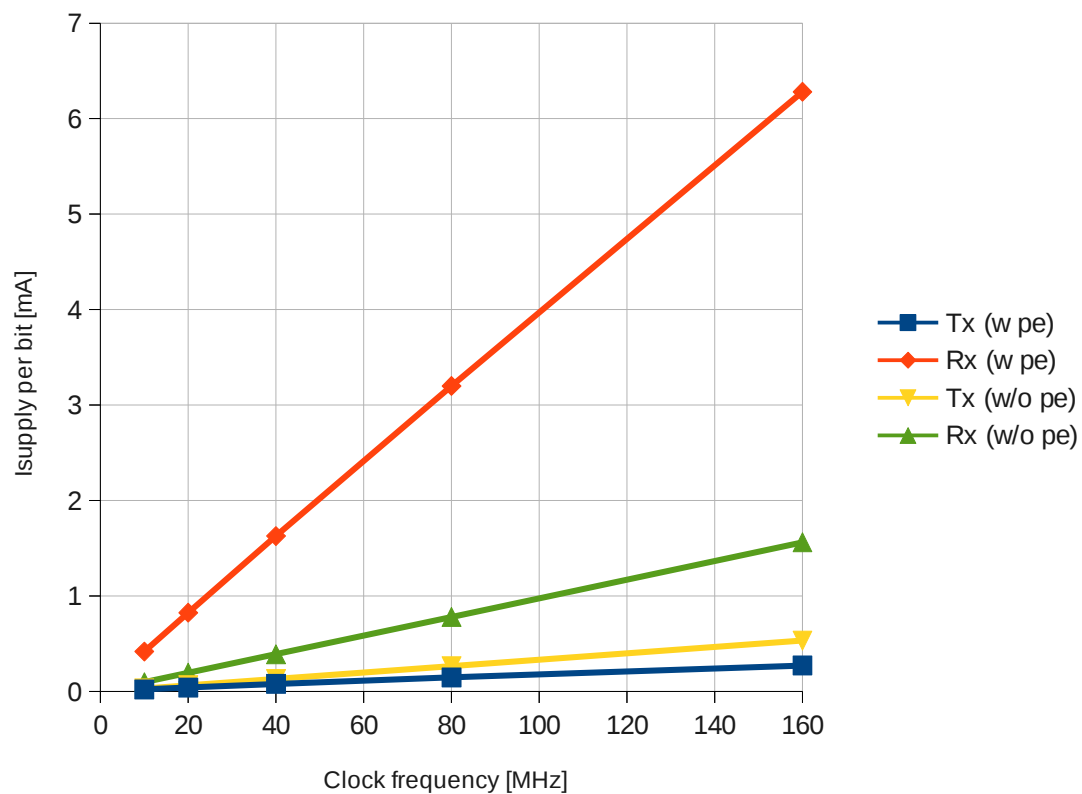




v4 Tx-Rx simulations



Sezione di Torino



Simulations of the new driver and 128 receivers for different frequencies assuming Gray encoding.

- * w pe : with reduced voltage swing and pre-emphasis
- * w/o pe : with full voltage swing and without pre-emphasis

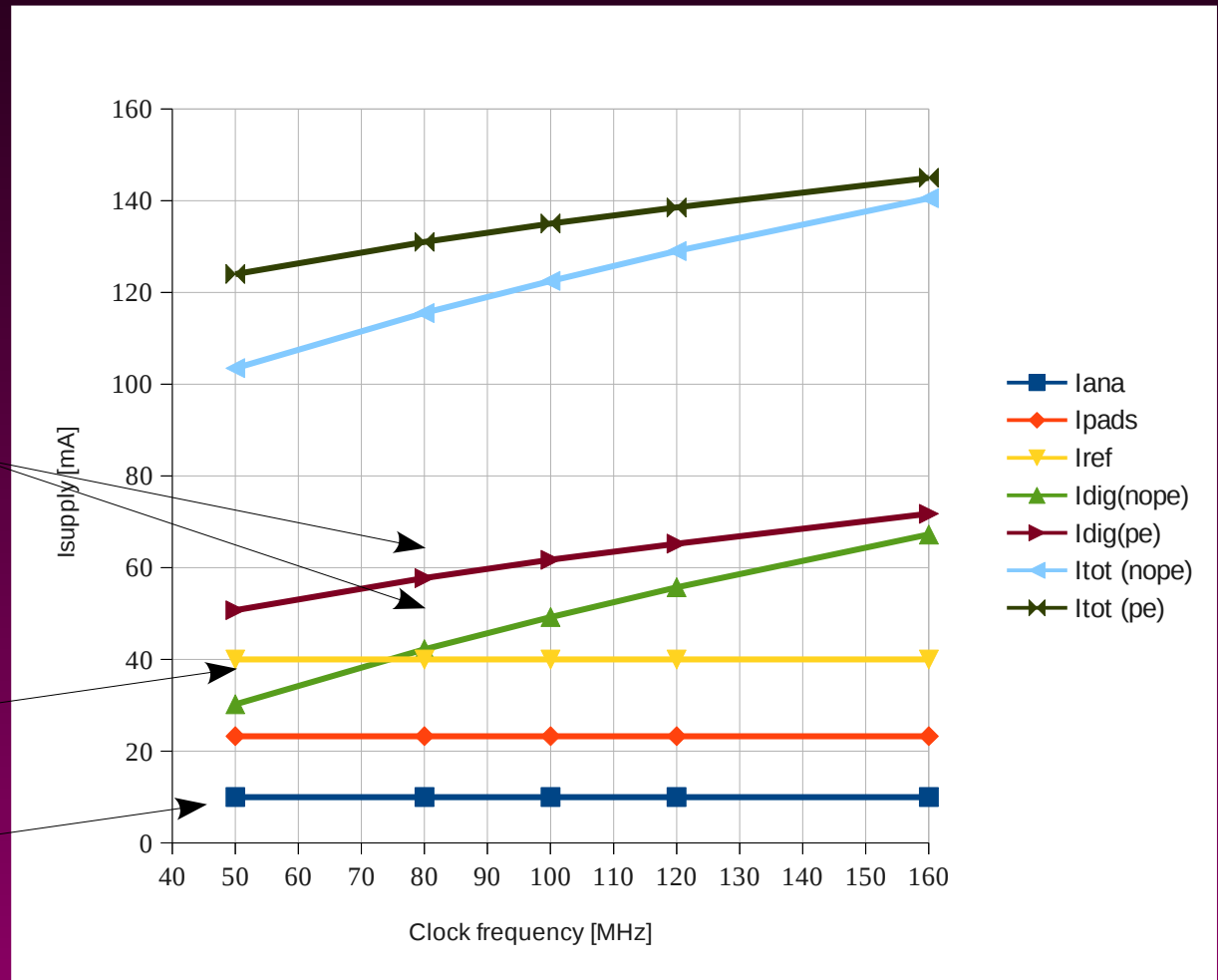
On pixel buffers takes the lion's share of the power consumption of the time stamp driver



ToPiX v3 supply



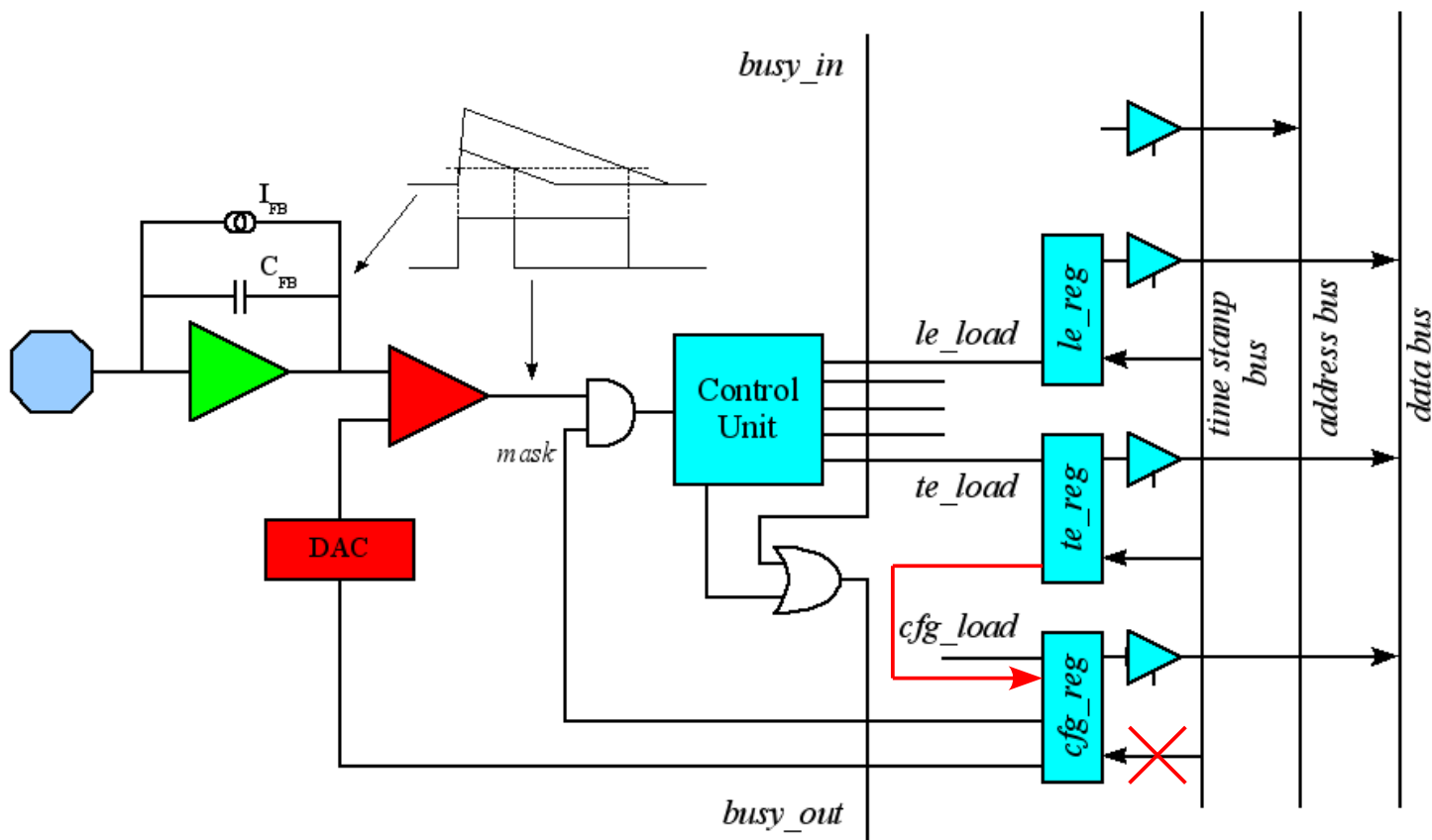
Sezione di Torino



55% from the time stamp counter

Can be made almost negligible (zero in theory)

15 $\mu\text{A}/\text{pixel}$



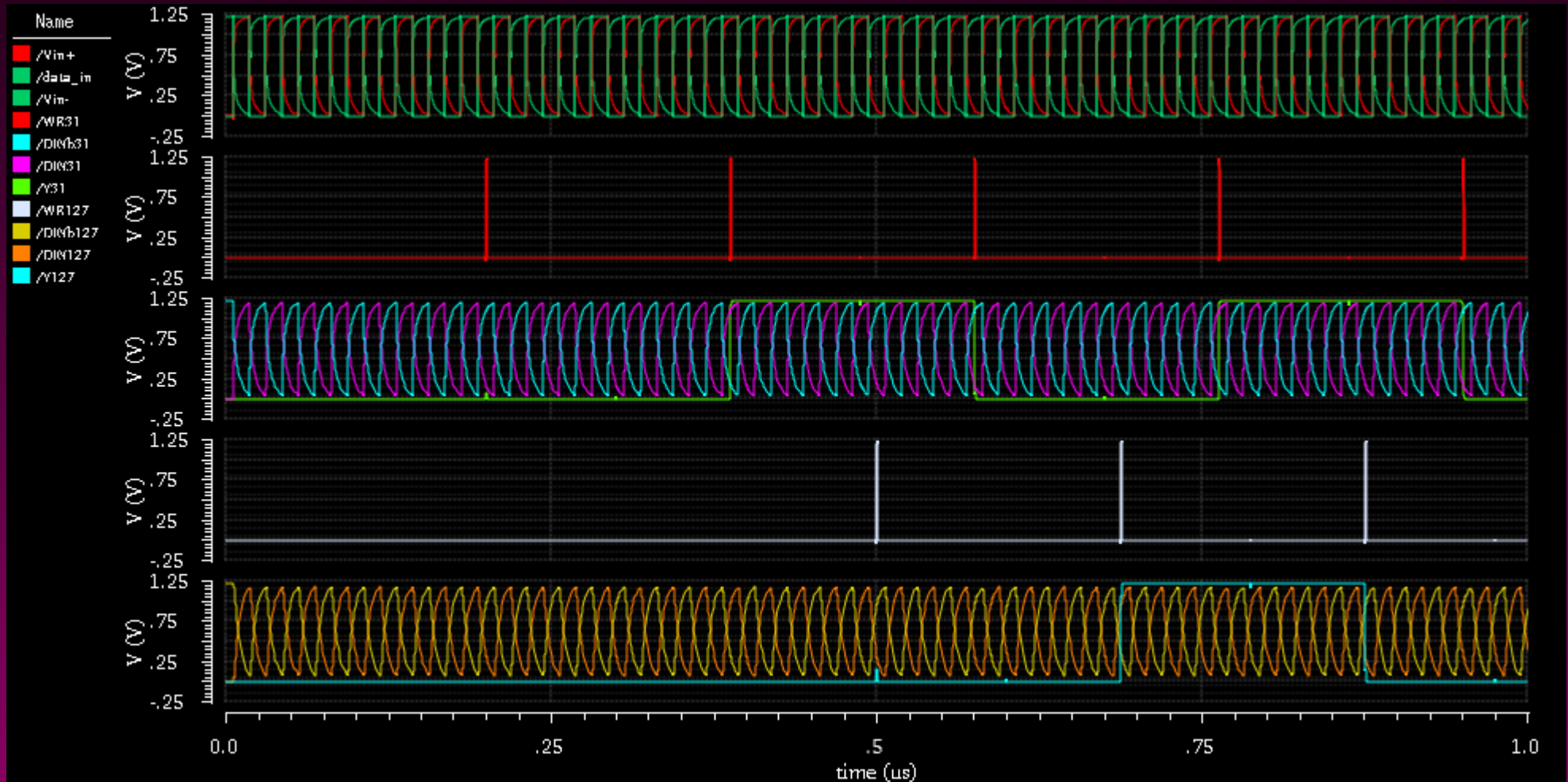
le_reg and te_reg are implemented via DICE-protected latches

cfg_reg is implemented with TMR/Hamming corrected DFF

Time stamp bus is NOT buffered at the pixel level



Time stamp transmission - no pe

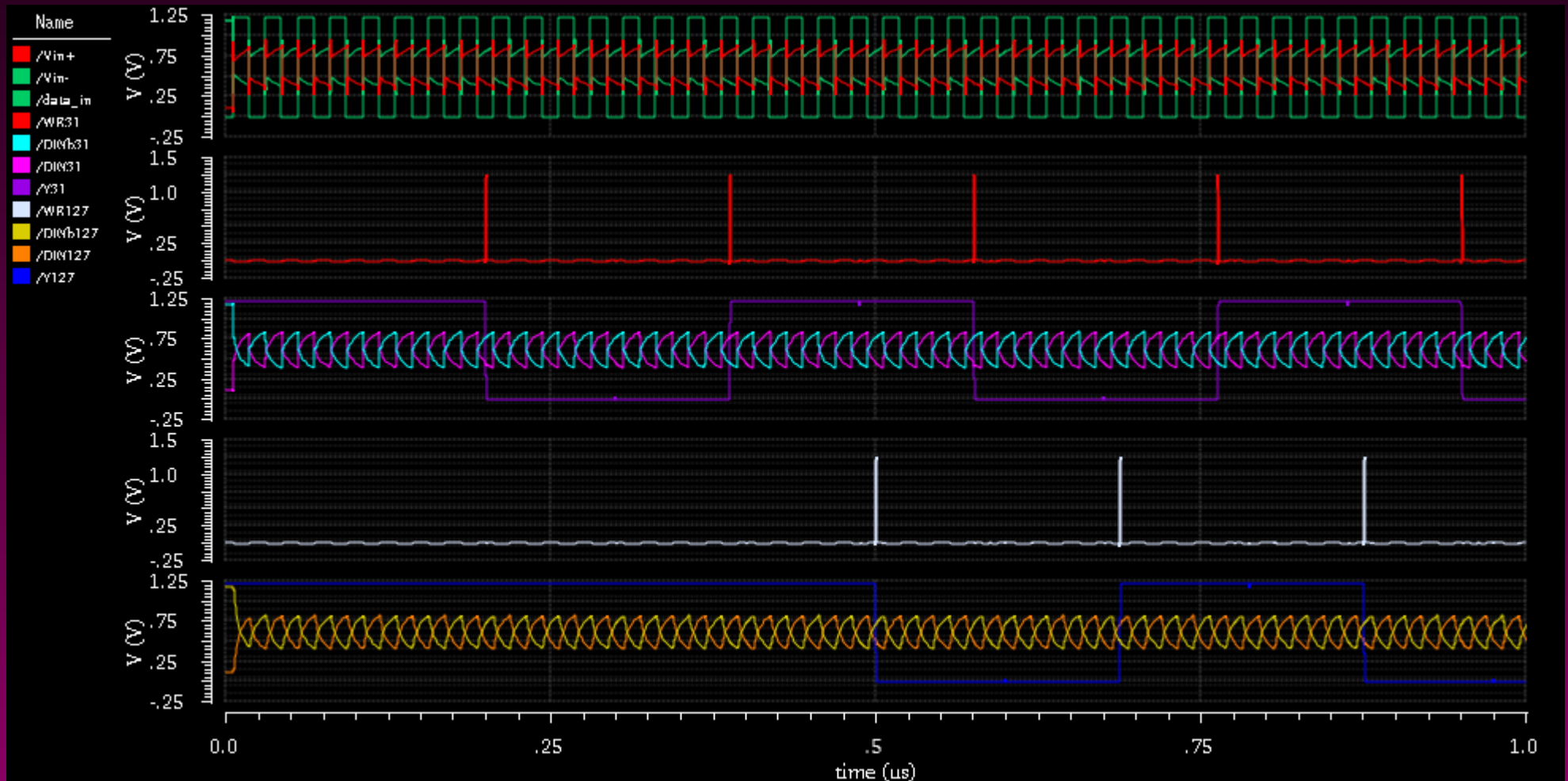




Time stamp transmission - pe



Sezione di Torino

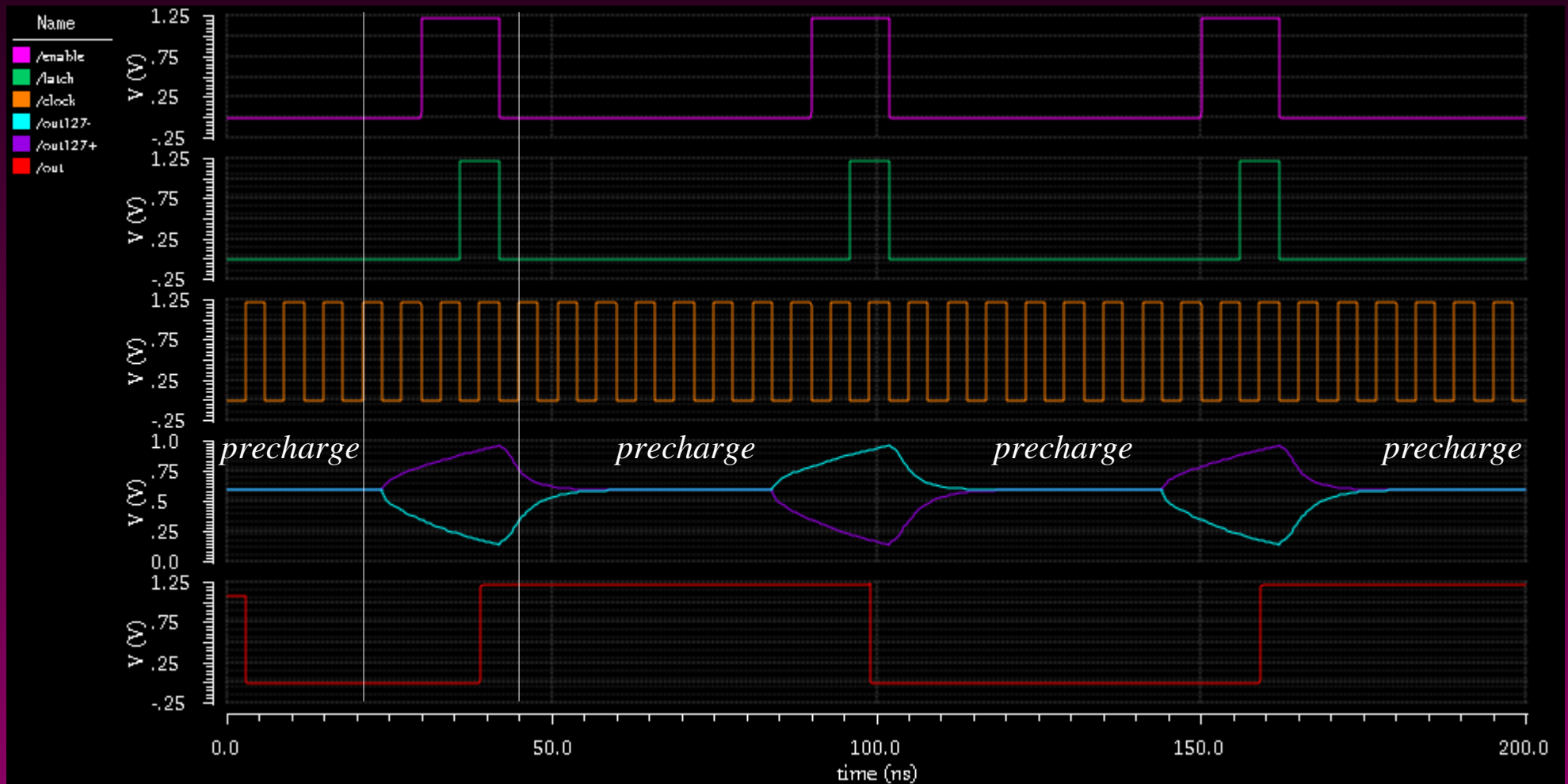




Bus readout



Sezione di Torino





Pixel cell SEU protection



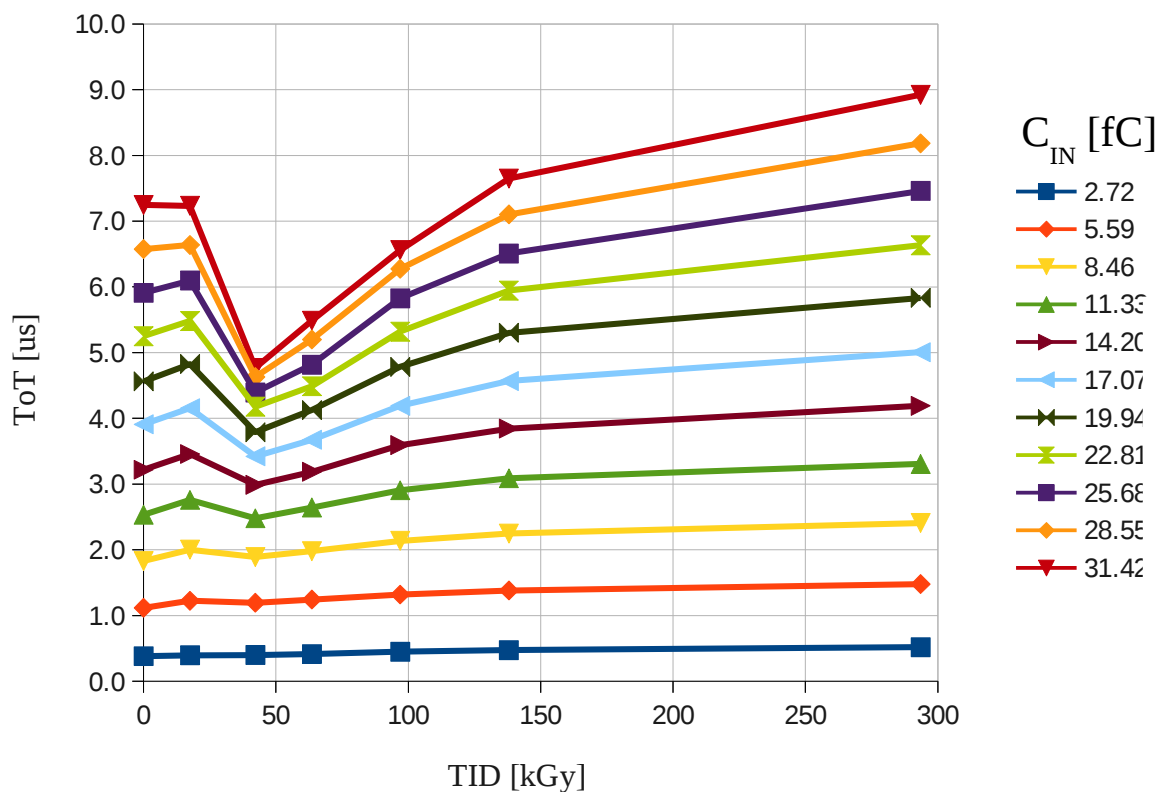
- * Leading edge and trailing edge registers will use latches with DICE scheme
 - * 12 bits register size : $4.8 \mu\text{m} \times 98.4 \mu\text{m}$
- * Configuration register will use DFF. Two possible protection schemes :
 - ✓ Hamming encoding with self correction
 - ✓ Triple redundancy
- * Automatic P&R for control logic and configuration register over an area of $39.2 \mu\text{m} \times 98.0 \mu\text{m}$. Occupancy is 82% for Hamming encoding and 90% for TMR.
- * Total on-pixel digital area : $50 \mu\text{m} \times 100.0 \mu\text{m}$ (as in ToPiX v3)



TID tests - ToT

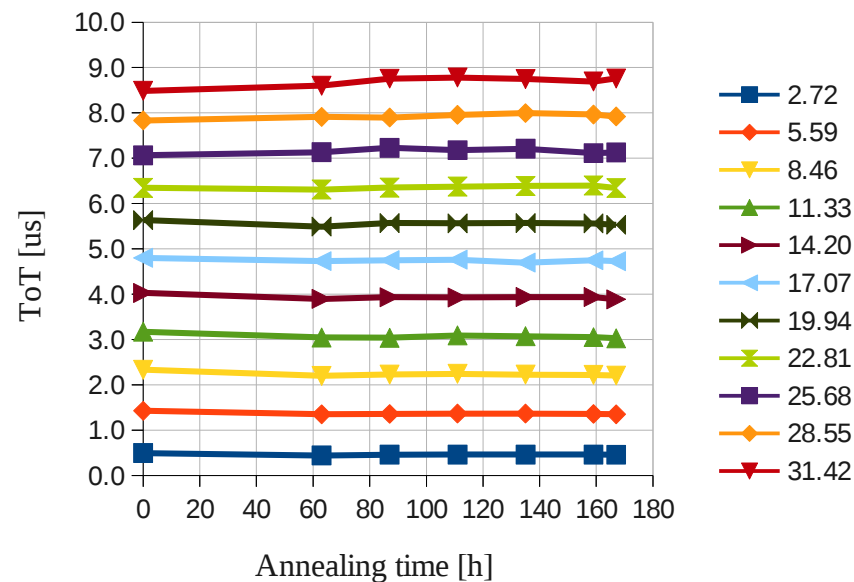


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During irradiation

Annealing @ 80 °C



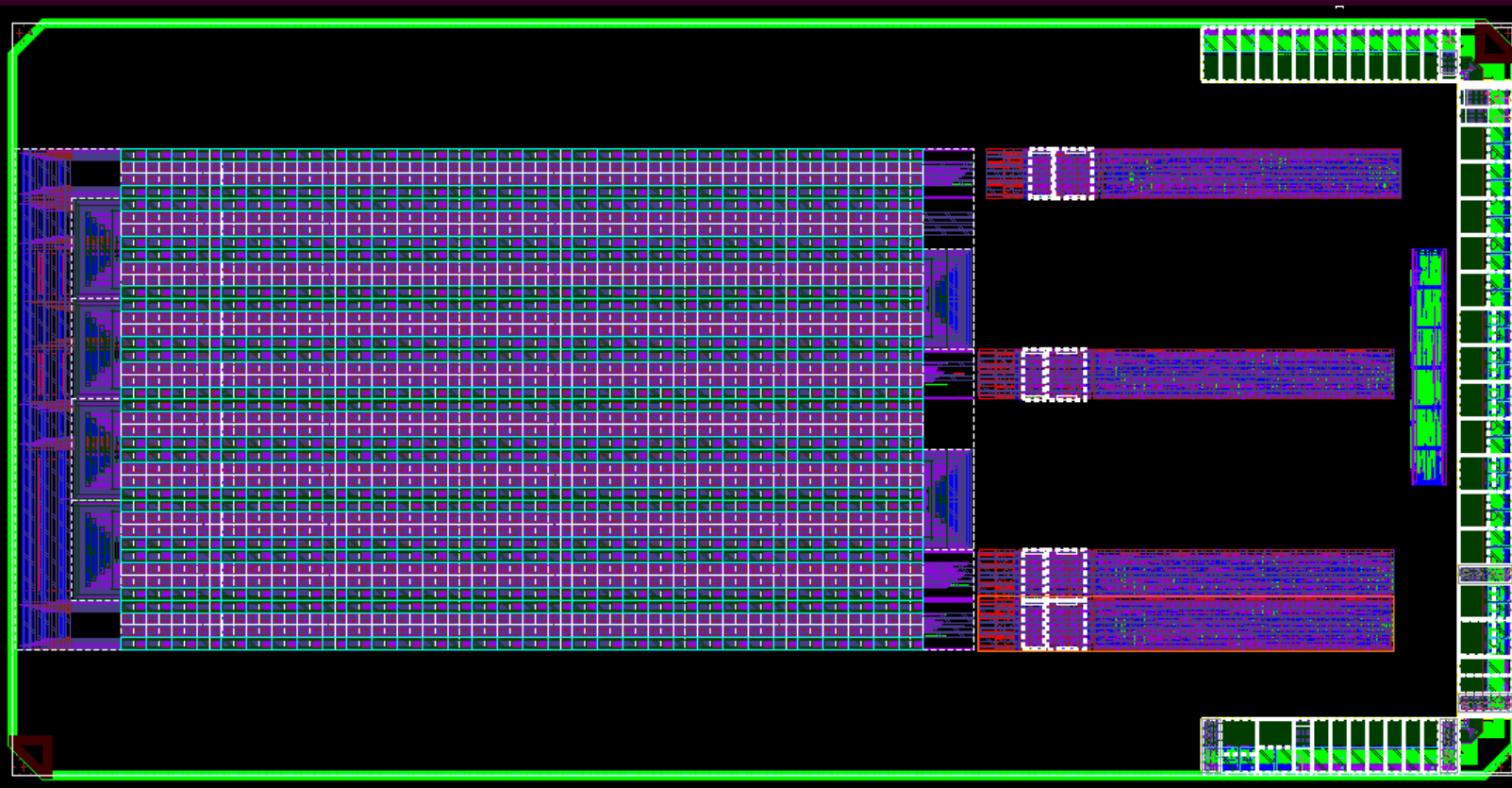
Probably due to effects in the clipping circuit – enclosed layout required ?



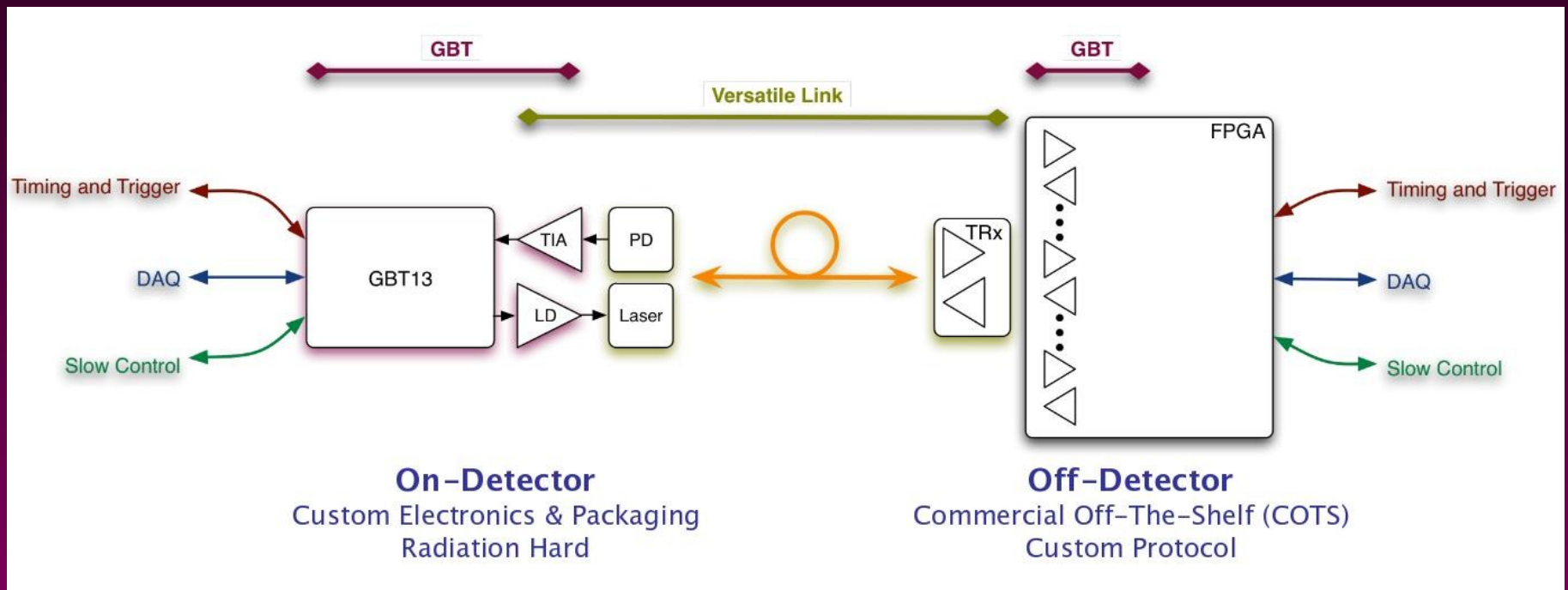
ToPiX v4



Sezione di Torino



- Size : 6 mm × 3 mm
- Compatible with v3 sensors
- CMOS 130 nm
- New pixel SEU protection scheme
- New column bus Tx and Rx
- Timing optimization and bug fixing
- GBT e-link interface

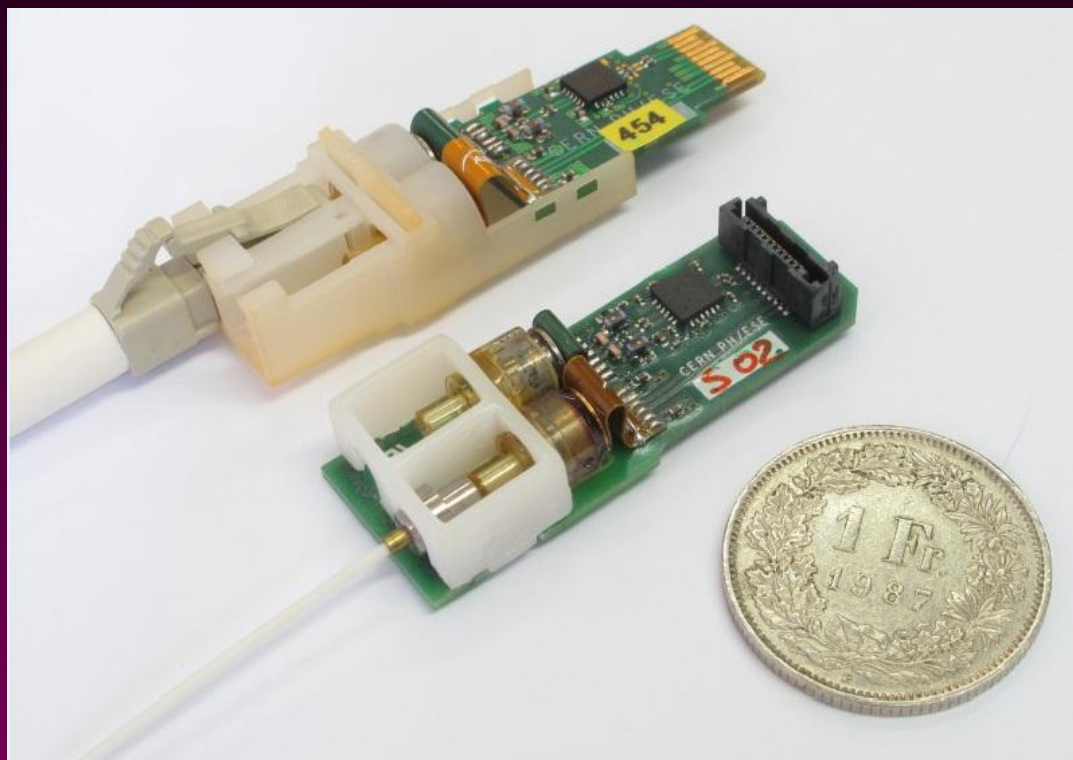




GBT components



Sezione di Torino



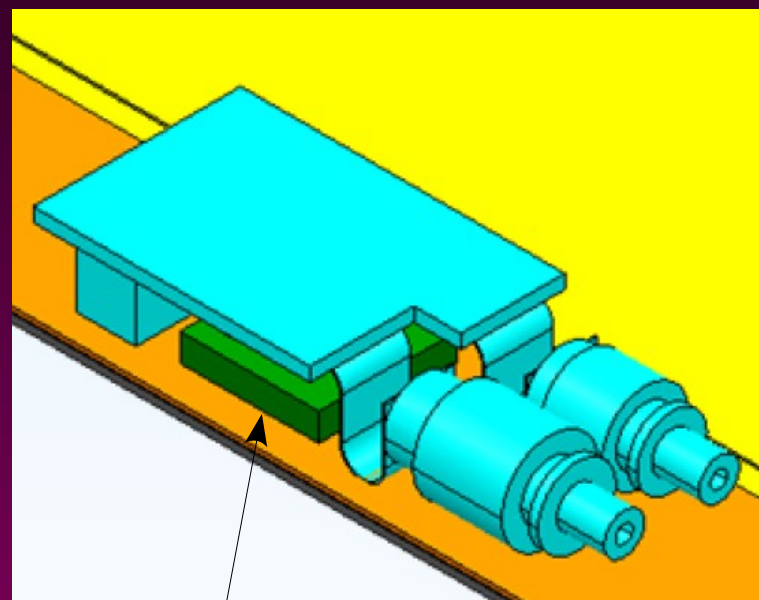
Versatile Transceiver

$50 \times 14 \times 10 \text{ mm}^3$

$45 \times 15 \times 8 \text{ mm}^3$

(F.Vasey, J.Troska, C.Soos)

Proposed arrangement
for CMS tracker (C.Soos)



GBTx $10 \times 10 \text{ mm}^2$
(P.Moreira et al.)



GBT status



- * GBTX :
 - * Final chip received, tests will start in May 2013 (*export license problems have delayed the packaging...*)
 - * Max power consumption 2.2 W (with all functionality on)
- * GBTIA :
 - * Version 2.0 ready for production – performances slightly worse than v1.0
 - * Version 2.1 (bug fixing) currently under test
- * GBLD :
 - * Current version (GBLD v4) can work up to 7.5 Gb/s with a power consumption of ~300 mW (with VCSELs)
 - * A low power version (GBLD v5) targeted at VCSELs has been submitted and is expected to return from foundry in June. Expected power saving 40% (up to 65% if double power supply is available)



GBT plans



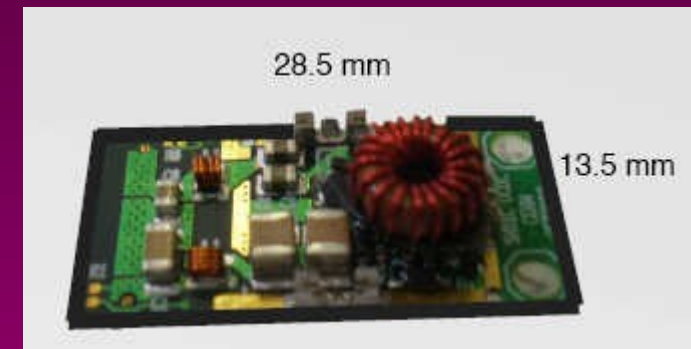
- * GBT chipset production foreseen in Q2 2014
- * To be installed by LHC experiments during LS2 (2018)
- * LpGBT : low power GBT
 - * Target power consumption : 500 mW (*75% reduction !*)
 - * Technology : CMOS 65 nm (apart from GBLD)
 - * 2 GBTX versions (LpGBT with SerDes only and full GBTX)
 - * High bandwidth (4.8 Gb/s downlink, 4.8/9.6 Gb/s uplink)
 - * Development will start in 2014
 - * *Not yet an approved project...*



Power regulator



- * ToPiX power supply $1.2 \text{ V} - I_{\text{DC}} \sim 1 \text{ A}$ (estimated)
→ *voltage drop on cables is not negligible*
- * A DC-DC converter solution compatible with the radiation levels and the magnetic field of a silicon tracker is under development @ CERN for sLHC
- * Current CERN version : $V_{\text{IN}} 10 \div 12 \text{ V}$, $V_{\text{OUT}} = 1.2 \div 3.3 \text{ V}$, $I_{\text{OUT}} < 3 \text{ A}$
- * $V_{\text{OUT}} = 1.5 \text{ V}$, $I_{\text{OUT}} < 3-4 \text{ A}$ now avail.
- * Tests with ToPiX v3 ongoing





Conclusions



- * Development of the ToPiX v4 has been delayed by concerns regarding radiation tolerance.
- * Pixel cell registers, bus drivers and precharge logic have been completely redesigned in order to increase speed while reducing power. Design is well advanced.
- * To be done :
 - Radiation tolerance improvement of the analog part
 - Chip control unit with GBTX interface
- * GBT project toward mass production in 1.5 years
- * Tests on voltage regulators and low mass cables ongoing



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Sezione di Torino

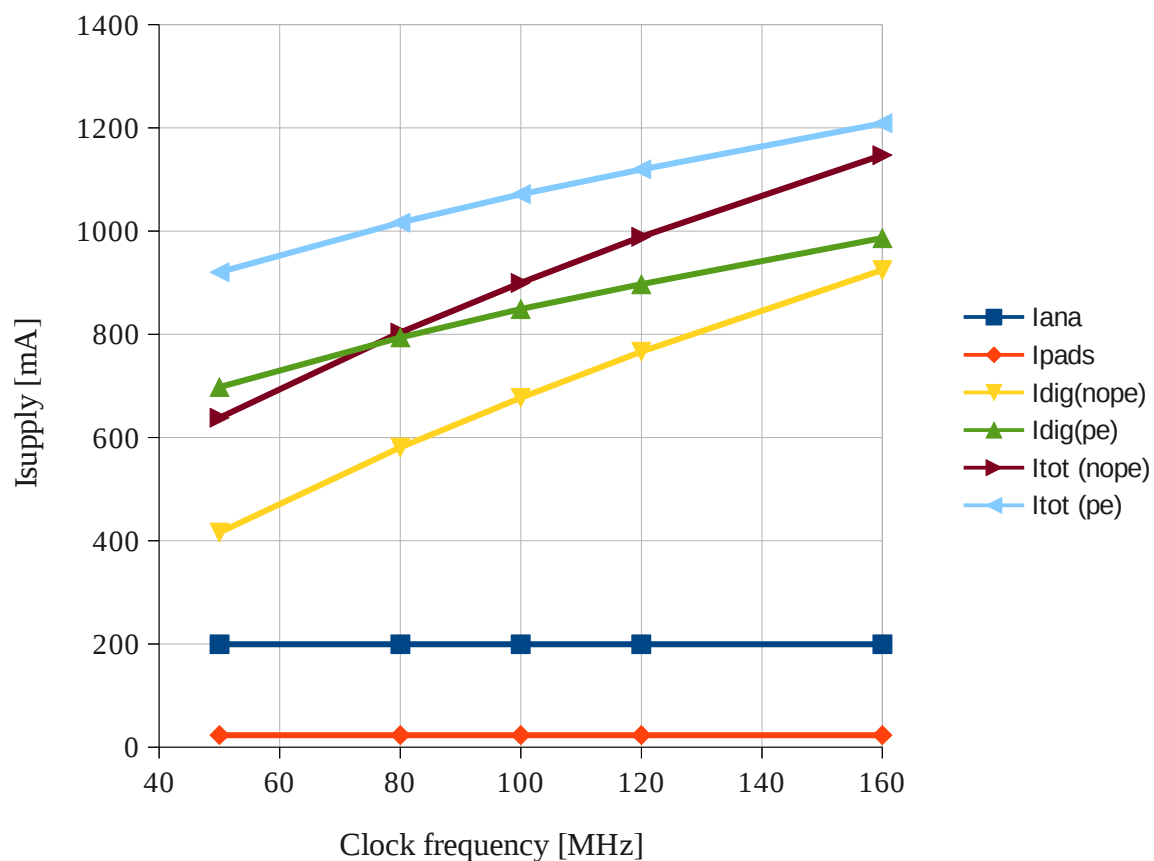
Backup slides



Full chip estimate



Sezione di Torino



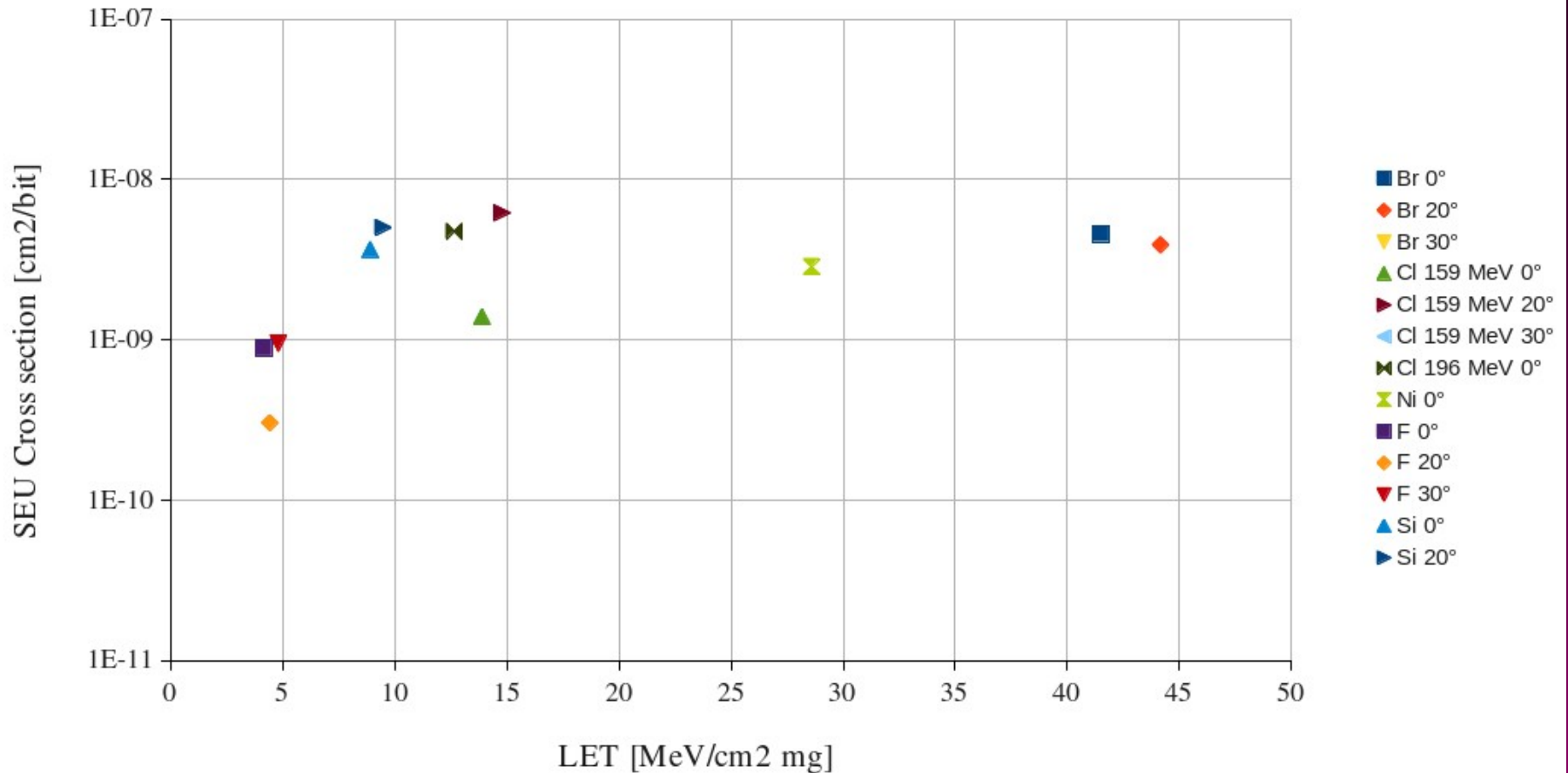
- * Very rough estimate
- * Still room for improvements (ToPiX v3 not really designed having low power in mind...)
- * Time stamp column drivers taken from NA62 GtkTo → room for improvement
- * However, power is dominated by digital logic, therefore it is $\propto f_{clock}$



GBLD I2C SEU results



Sezione di Torino

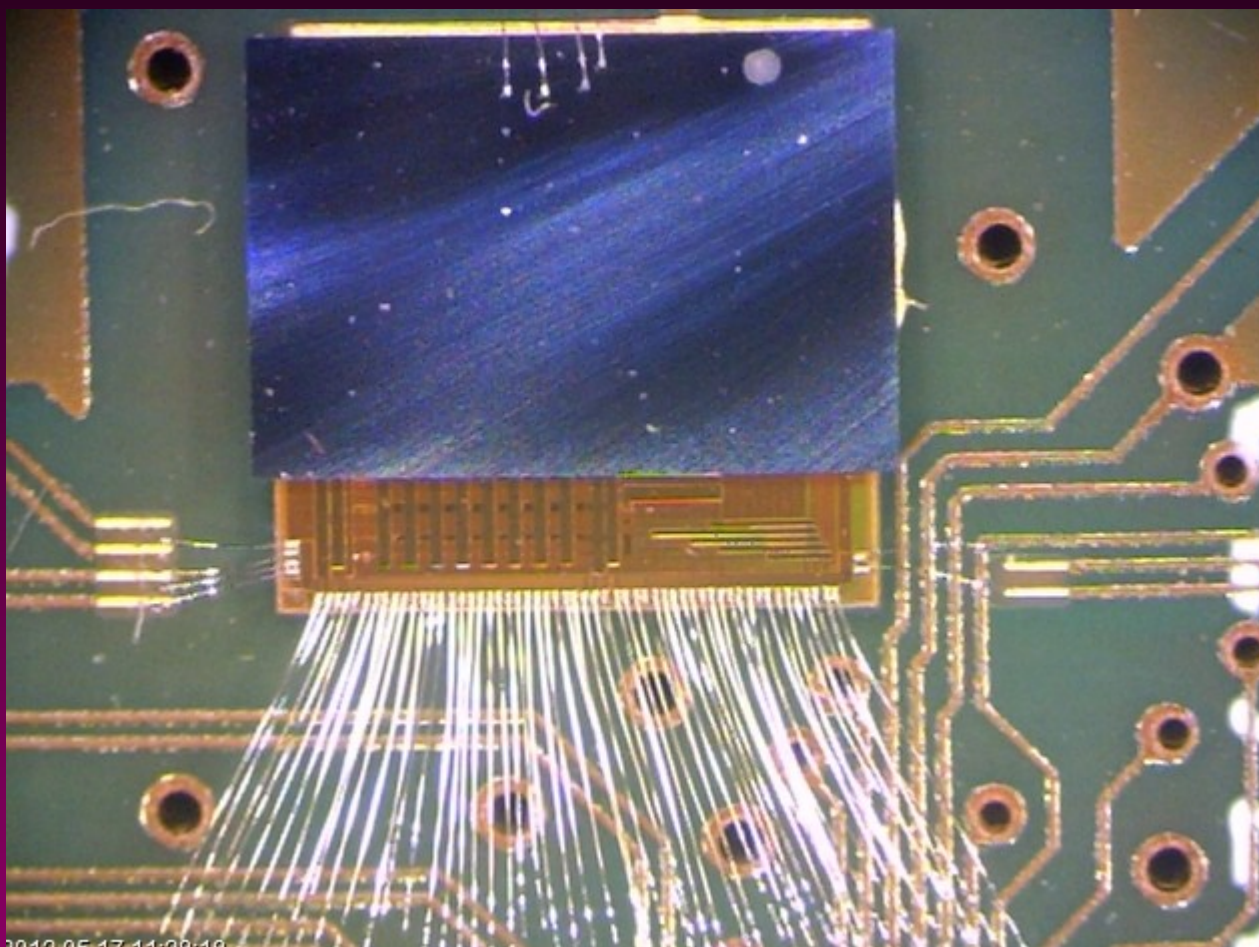


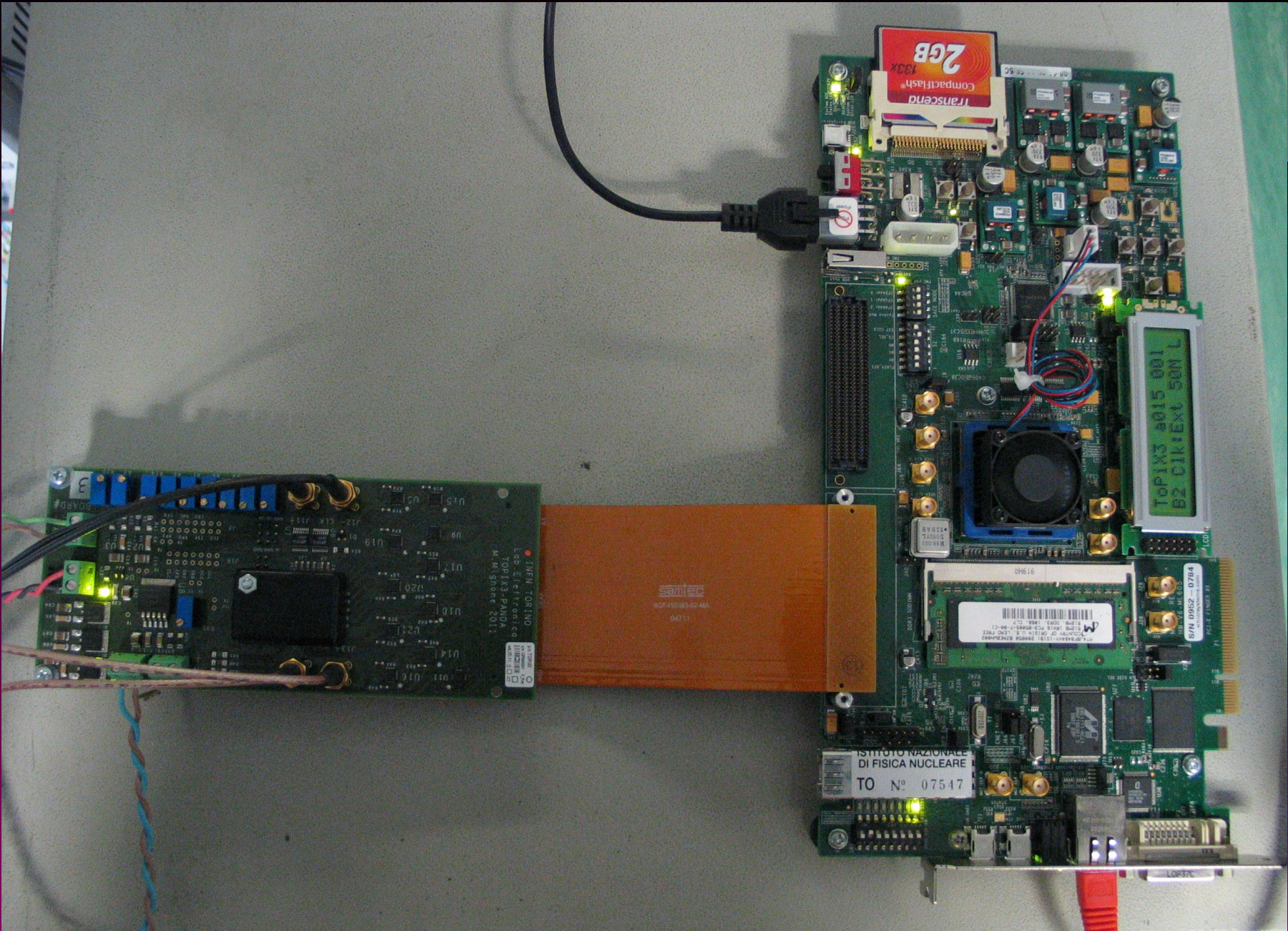


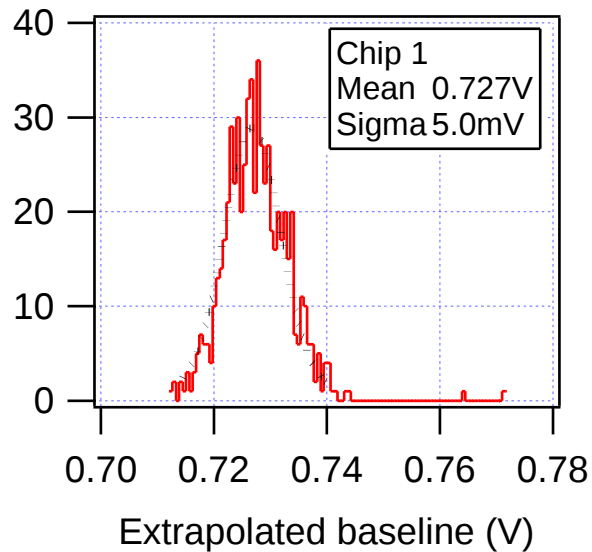
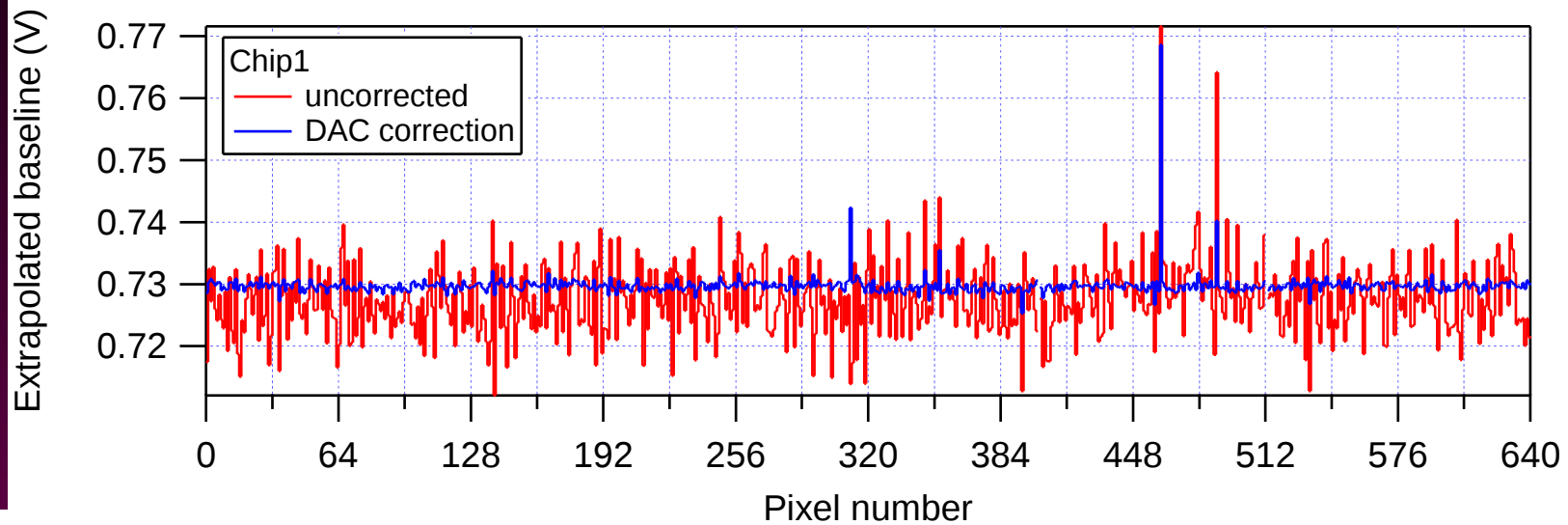
ToPiX + sensor



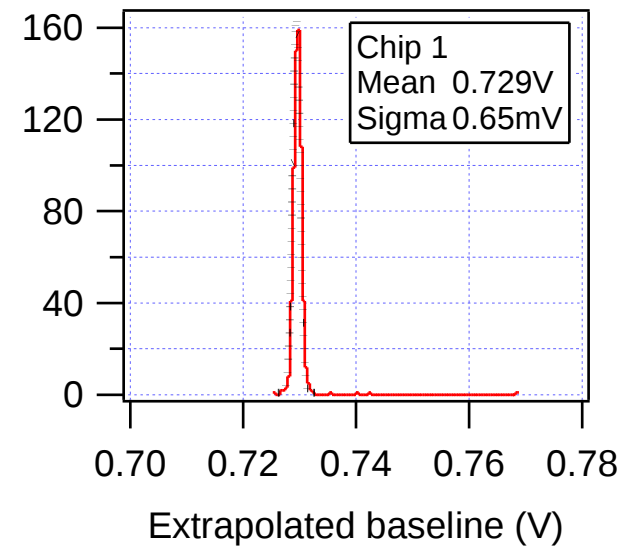
Sezione di Torino





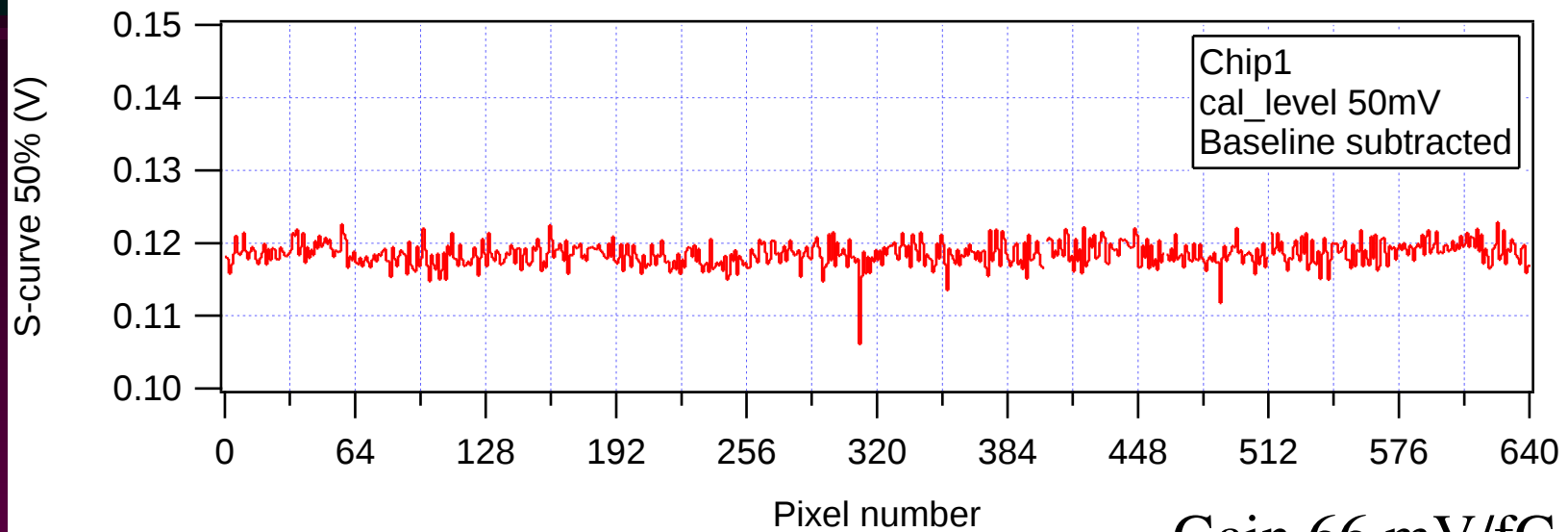


*DAC
correction*

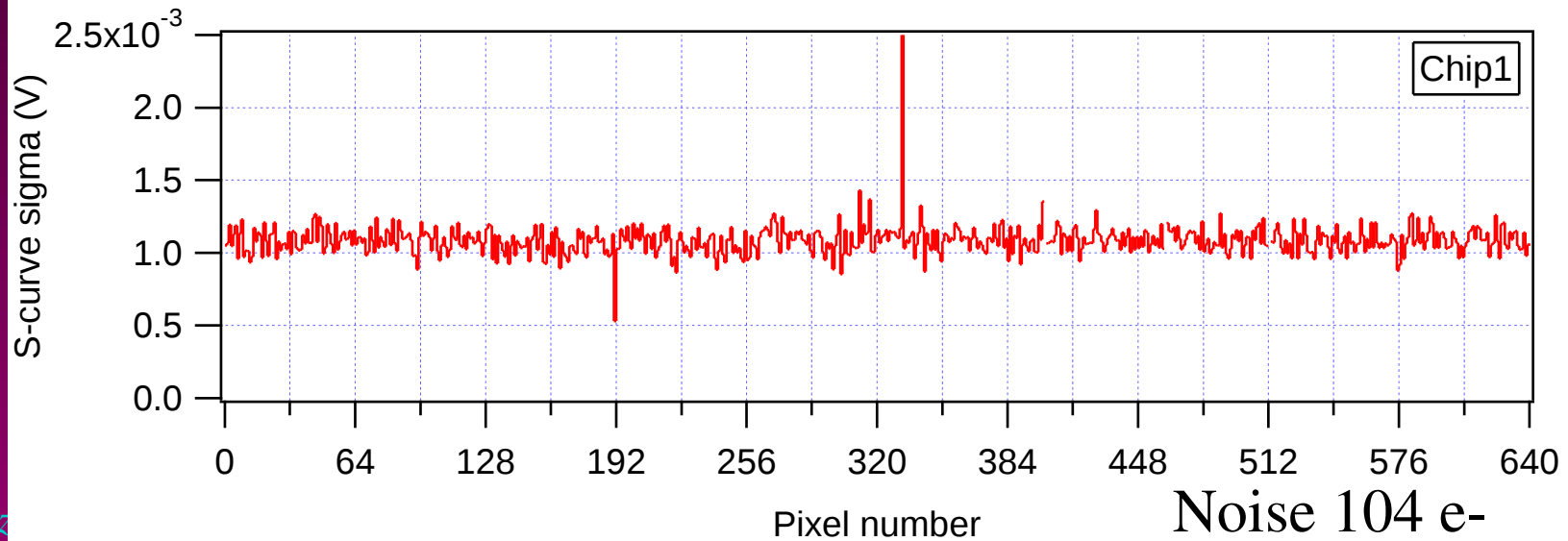




Gain & Noise



Gain 66 mV/fC



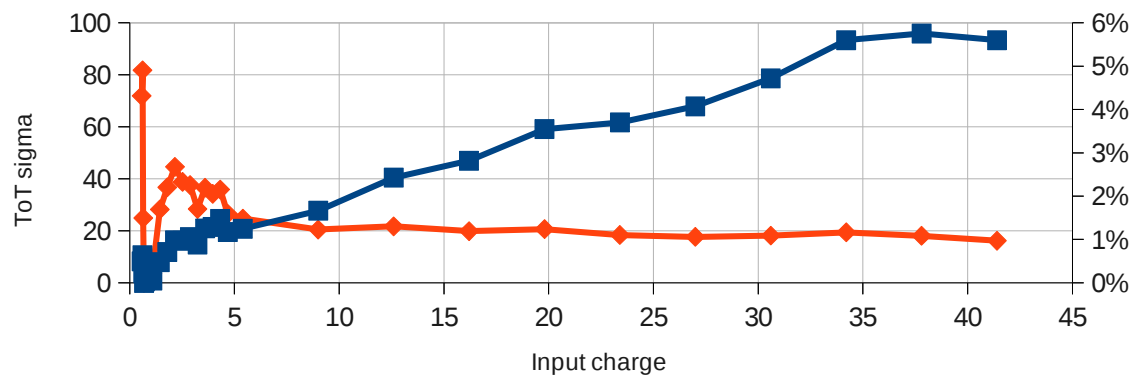
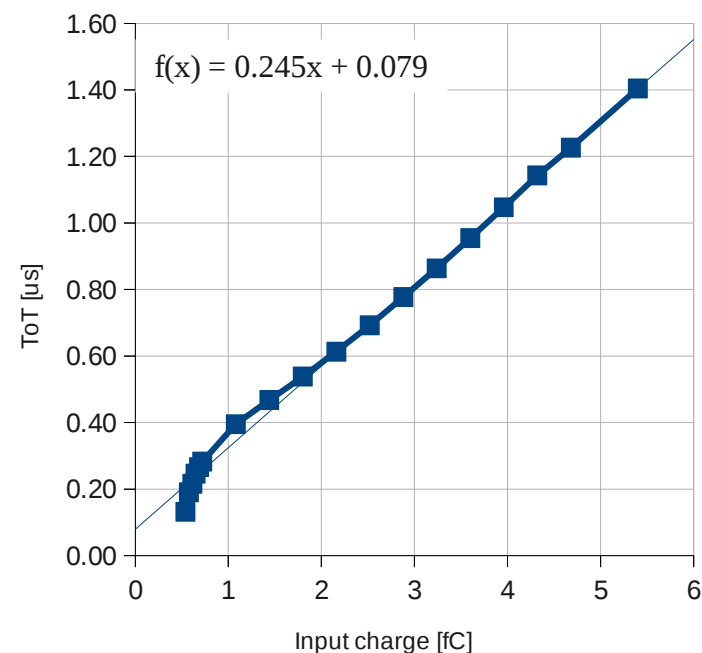
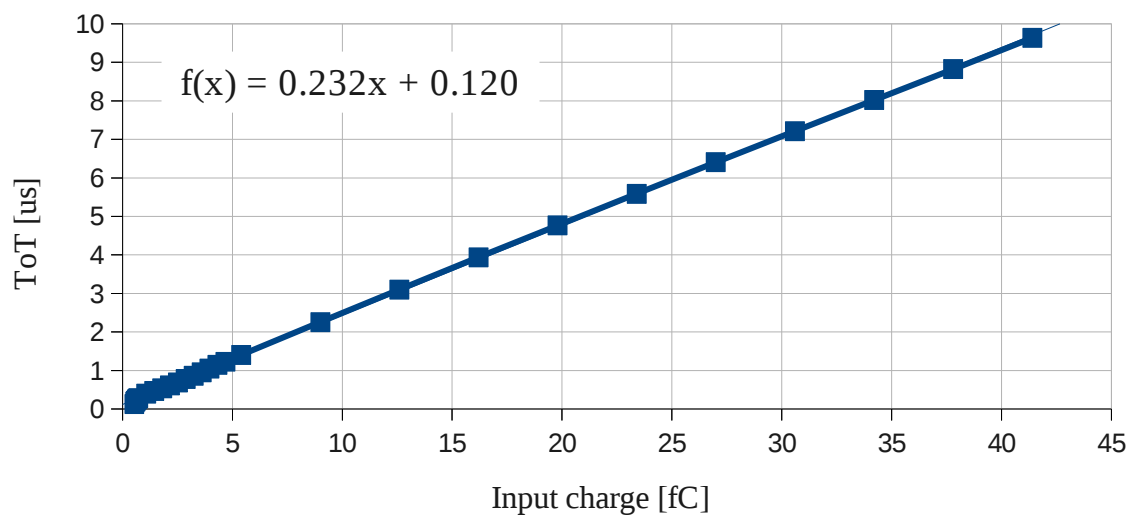
Noise 104 e-



ToT @ 5 nA



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$$I_{FB} = 5 \text{ nA}$$

Simulated gain : 202 ns/fC



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